

Vishay Siliconix

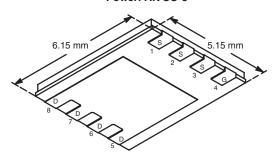
N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
100	0.014 at V _{GS} = 10 V	60	47.5 nC			

FEATURES

- Halogen-free
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

PowerPAK SO-8

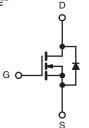


Bottom View

Ordering Information: Si7178DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- Primary Side Switch
- POL
- Intermediate Bus Converter



N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	IGS T _A = 25 °C,	unless other	rwise noted	
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C		60	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		48	
Continuous Diam Current (1) = 130 C)	T _A = 25 °C] ' ^D [14.9 ^{b, c}	
	T _A = 70 °C	1	11.9 ^{b, c}	Α
Pulsed Drain Current	•	I _{DM}	80	
Continuous Source-Drain Diode Current	T _C = 25 °C		60	
Continuous Source-Drain Diode Current	T _A = 25 °C	Is	5.2 ^{b, c}	
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	40	
Single Pulse Avalanche Energy		E _{AS}	80	mJ
	T _C = 25 °C		104	
Maximum Power Dissipation	T _C = 70 °C	P_{D}	66.5	w
Maximum Fower Dissipation	T _A = 25 °C] '' [6.25 ^{b, c}	VV
	T _A = 70 °C	1	4.0 ^{b, c}	
Operating Junction and Storage Temperatur	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera		260		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, f}	t ≤ 10 s	R_{thJA}	15	20	°C/W		
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	0.9	1.2	O/ VV		

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

 e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 54 °C/W.

Si7178DP

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	1		I.	'		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		130		1./20
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 10		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2.5		4.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			1 10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A		0.0114	0.014	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		28		S
Dynamic ^b	1 5.5			<u> </u>		
Input Capacitance	C _{iss}			2870		
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		225		pF
Reverse Transfer Capacitance	C _{rss}			91		
Total Gate Charge	Q_g			47.5	72	
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		13.2		nC
Gate-Drain Charge	Q _{gd}			12.7		
Gate Resistance	R _g	f = 1 MHz	0.3	1.15	2.3	Ω
Turn-On Delay Time	t _{d(on)}			18	35	
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		10	20	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, $V_{GEN}=10$ V, $R_g=1$ Ω		27	50	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}			21	40	ns
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		10	20	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, $V_{GEN}=8$ V, $R_g=1$ Ω		27	50	
Fall Time	t _f			11	20	
Drain-Source Body Diode Characteristi	cs					•
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			60	A
Pulse Diode Forward Current ^a	I _{SM}				80	_ ^
Body Diode Voltage	V_{SD}	I _S = 4 A		0.76	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			64	100	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A di/dt = 100 A/us T = 25 °C		200	300	nC
Reverse Recovery Fall Time	ta	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		51		
Reverse Recovery Rise Time	t _b			13		ns

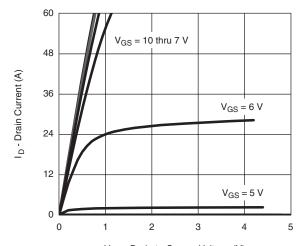
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



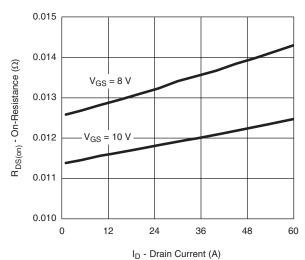
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

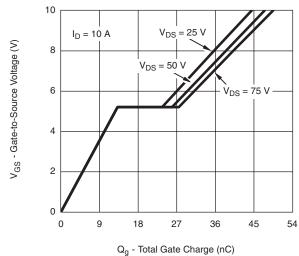


 $V_{\mbox{\scriptsize DS}}$ - Drain-to-Source Voltage (V)

Output Characteristics

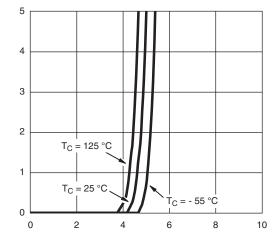


On-Resistance vs. Drain Current



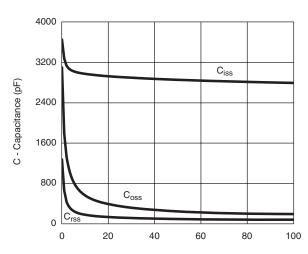
Gate Charge

I_D - Drain Current (A)



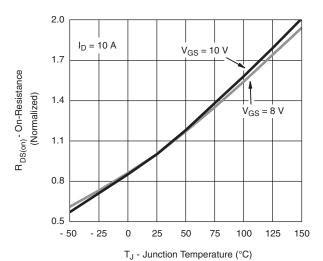
V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



 V_{DS} - Drain-to-Source Voltage (V)

Capacitance



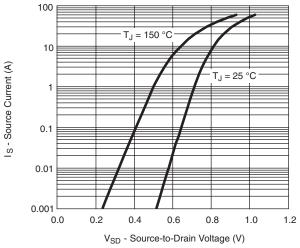
On-Resistance vs. Junction Temperature

Si7178DP

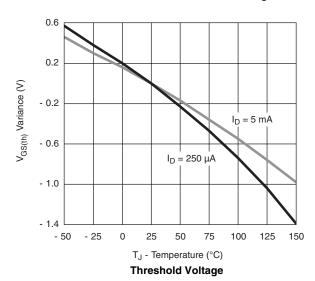
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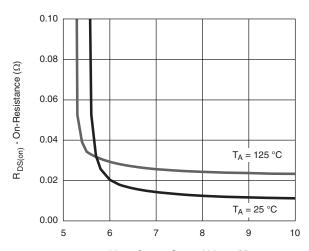
VISHAY

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

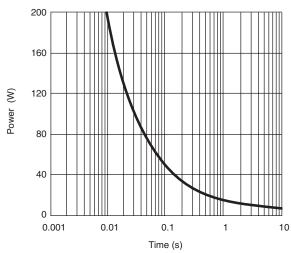


Source-Drain Diode Forward Voltage

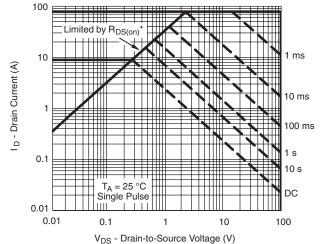




 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\$ On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



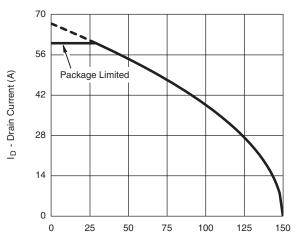
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area, Junction-to-Ambient



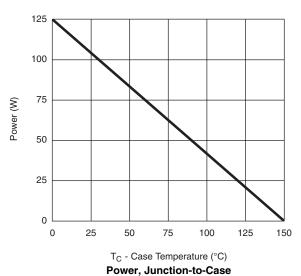
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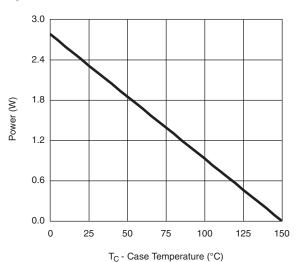
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*





Power, Junction-to-Ambient

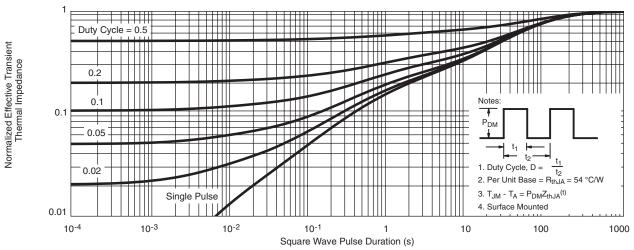
^{*} The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

Si7178DP

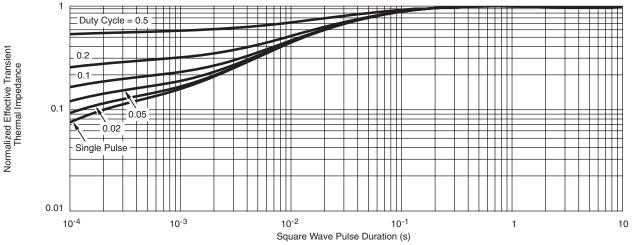
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?69951.



DWG: 5881

PowerPAK® SO-8, (Single/Dual)



3. Dimensions exclusive of mold flash and cutting burrs.							
DIM.		MILLIMETERS		INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
	4.00	4.00	F 00	0.400	0.400	0.407	

Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4		0.57 typ.			0.0225 typ.		
D5		3.98 typ.			0.157 typ.		
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2 (for AL product)	3.30	3.48	3.66	0.130	0.137	0.144	
E2 (for other product)	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4 (for AL product)	0.58 typ. 0.023 typ.						
E4 (for other product)		0.75 typ.			0.030 typ.		
е		1.27 BSC		0.050 BSC			
K (for AL product)		1.45 typ.		0.057 typ.			
K (for other product)		1.27 typ.		0.050 typ.			
K1	0.56	-	=	0.022	-	=	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
M	0.125 typ.			0.005 typ.			
ECN: C13-0702-Rev. K, 20)-May-13			•			

Revison: 20-May-13 Document Number: 71655



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



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Revision: 02-Oct-12 Document Number: 91000